



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SERIES: HSE-BX-01 | **DESCRIPTION:** HEAT SINK

FEATURES

- TO-220 package
- round or slot hole option
- low profile



MODEL

MODEL	mounting hole		thermal resistance ¹				power dissipation ¹
	type	size (mm)	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSE-B2111-038	round	Ø3.8	19.74	20.99	6.12	5.18	3.80
HSE-B1711-032	round	Ø3.2	20.27	22.39	6.84	5.05	3.70
HSE-B1711-057	slot	3.2 x 5.7	24.19	24.30	7.07	5.79	3.10

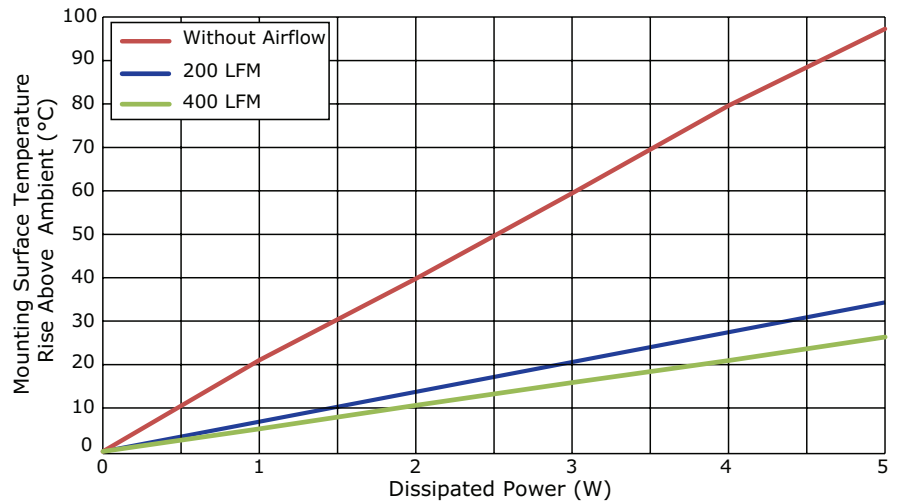
Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

HSE-B2111-038

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	20.99	6.12	5.18
2	39.76	13.23	10.62
3	59.46	19.90	15.87
4	79.61	26.92	20.94
5	97.29	34.35	26.37

T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

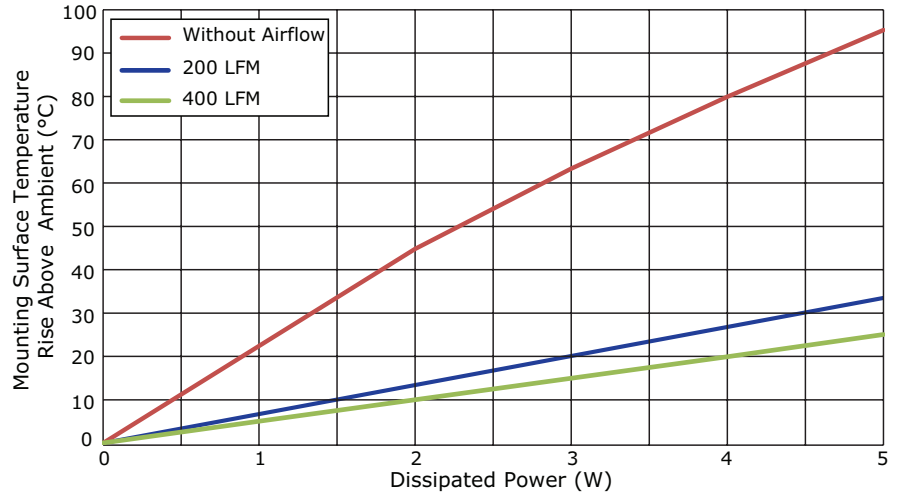


PERFORMANCE CURVES (CONTINUED)

HSE-B1711-032

Power (W)	Heatsink Temperature Rise Above Ambient ($\Delta T = T_{hs} - T_a$) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	22.39	6.84	5.05
2	44.78	13.44	9.99
3	63.30	20.16	14.97
4	79.94	26.86	19.95
5	95.30	33.50	25.04

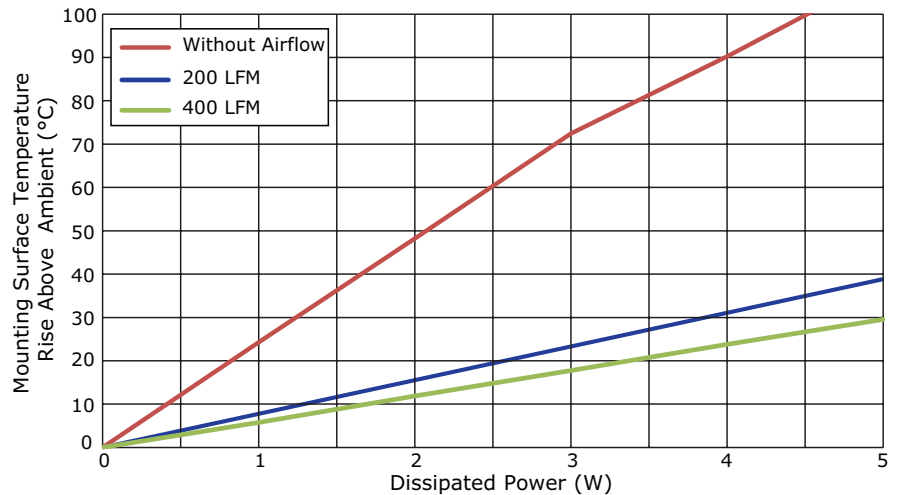
T_{hs} : "hot spot" temperature measured on the heatsink
 T_a : ambient temperature



HSE-B1711-057

Power (W)	Heatsink Temperature Rise Above Ambient ($\Delta T = T_{hs} - T_a$) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	24.30	7.07	5.79
2	48.19	15.28	11.89
3	72.44	22.86	17.72
4	90.24	30.47	23.81
5	109.19	38.84	29.57

T_{hs} : "hot spot" temperature measured on the heatsink
 T_a : ambient temperature

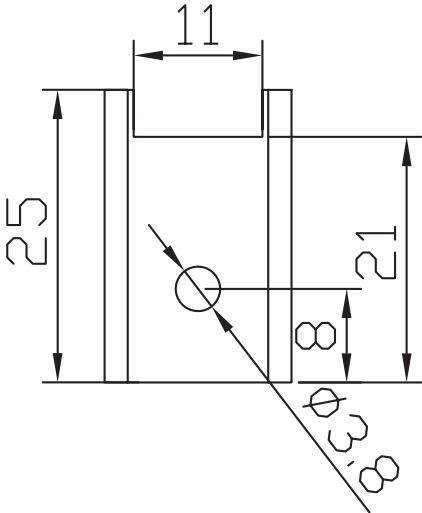


MECHANICAL DRAWING

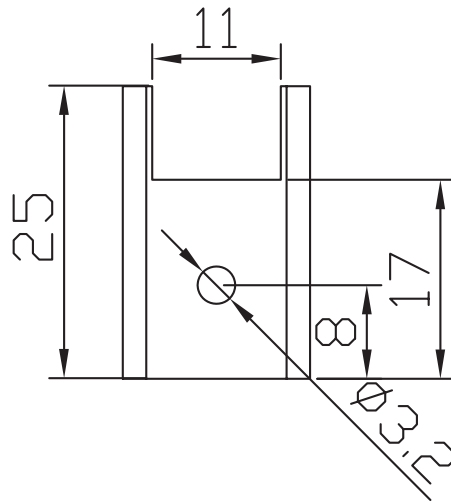
units: mm
tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	4.4 g

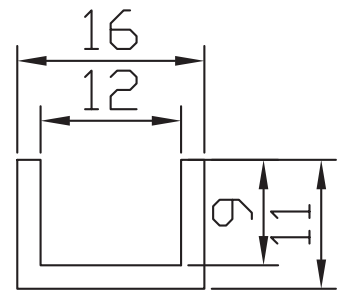
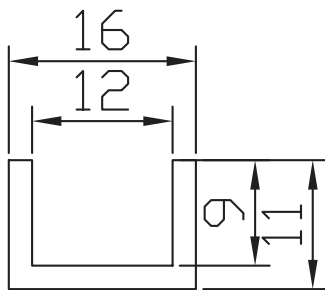
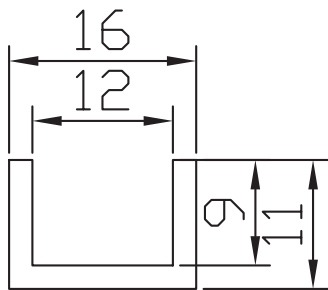
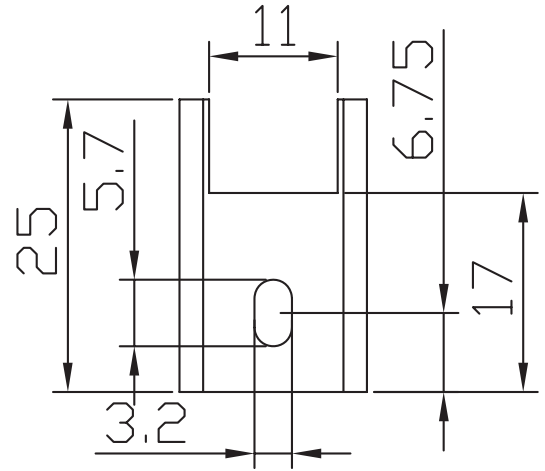
HSE-B2111-038



HSE-B1711-032



HSE-B1711-057



REVISION HISTORY

rev.	description	date
1.0	initial release	05/09/2017

The revision history provided is for informational purposes only and is believed to be accurate.



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